

## EIA Standards Committees

### S-1 Steering Committee

**Committee Scope:** The S-1 Passive Component Steering Committee's scope is to provide leadership and direction for passive component standards engineering working groups. The Committee will offer an opportunity for creating a unifying environment for interaction between all passive component users and producers.

**Committee Chairman:** Representative from IBM Corp.

### CE-2.0 National Connector and Socket Standards Committee

**Committee Scope:** The committee is populated by experienced individuals, including a number of those responsible for labs themselves, including manufacturers of MIL connectors. The CE-2.0 committee is responsible for developing standards for electronic connectors and sockets and associated hardware. It is most well-known for the EIA 364-series of test procedures, which are used globally and adopted by the US DoD. The committee typically meets face-to-face several times annually and conducts business between meetings through the ECIA electronic workspace. [364 Series Library Committee Access Link](#)

**Committee Chairman:** Frank Ruffino, Molex Incorporated

### P-2.1 Ceramic Dielectric Capacitors

**Committee Scope:** All types of Ceramic Dielectric Capacitors

**Committee Chairman:** Michael Cannon, TDK Corporation of America

### P-1 Resistive Devices

**Committee Scope:** All types of resistive components regardless of technology. Includes composition, film, wirewound, thermistors, varistors, networks, chip resistors and integrated passive devices.

**Committee Chairman:** Joseph Biernacki, Stackpole Electronics

### P-3 Inductive Components

**Committee Scope:** The Committee approved (7 Oct. 1998) a change in the scope of the P-3, Inductive Components Committee. "This committee covers all types of inductive components regardless of technology used in electronic circuits. It includes inductors, rf. (chokes, filters, interference filters, inductors and transformers), chip inductors, and variable inductors."

**Committee Chairman:** Joseph Biernacki, Stackpole Electronics

### ACH Automated Component Handling

**Committee Scope:** Develop and maintain engineering standards and publications for tape, reels, magazines, trays, etc. for handling components in production. Also, provide technical input to US national positions on related international standards issues and proposals.

**Committee Chairman:** Brian Matheny, TEKPAK Inc.

## P-2.2 Paper, Film, Mica & Wet-Electrolytic Capacitors

**Committee Scope:** Paper, film, mica and wet-electrolytic capacitors for all AC and DC applications, except inductive heating and utility power-factor correction.

**Committee Chairman:** Open

## P-2.5 Solid Electrolytic Capacitors

**Committee Scope:** All types of Tantalum Capacitors

**Committee Chairman:** Keith Moore, KEMET Electronics

## Dependability

**Committee Scope:** Develop and maintain domestic standards related to dependability. Dependability covers the availability performance and its influencing factors: reliability performance, maintainability performance and maintenance support performance (including management of obsolescence). The standards provide systematic methods and tools for the dependability assessment and management of equipment, services and systems throughout their life cycles.

**Committee Chairman:** Lisa Bates, Raytheon

## Soldering Technology

**Committee Scope:** The STC encompasses soldering practices (soldering iron-mass reflow techniques) and associated soldering materials (solders, pastes and adhesives, and flux/cleaning agents). However, the Committee will focus on solderability test method development for printed through-hole (PTH) and surface mountable components. One of the major functions is to promote commonality and standardization of soldering test methodology within the EIA Sectors.

**Committee Chairman:** Doug Romm, Texas Instruments Inc.

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